

HD74LS86

Quadruple 2-input Exclusive-OR Gates

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Rev.2.00
Feb.18.2005

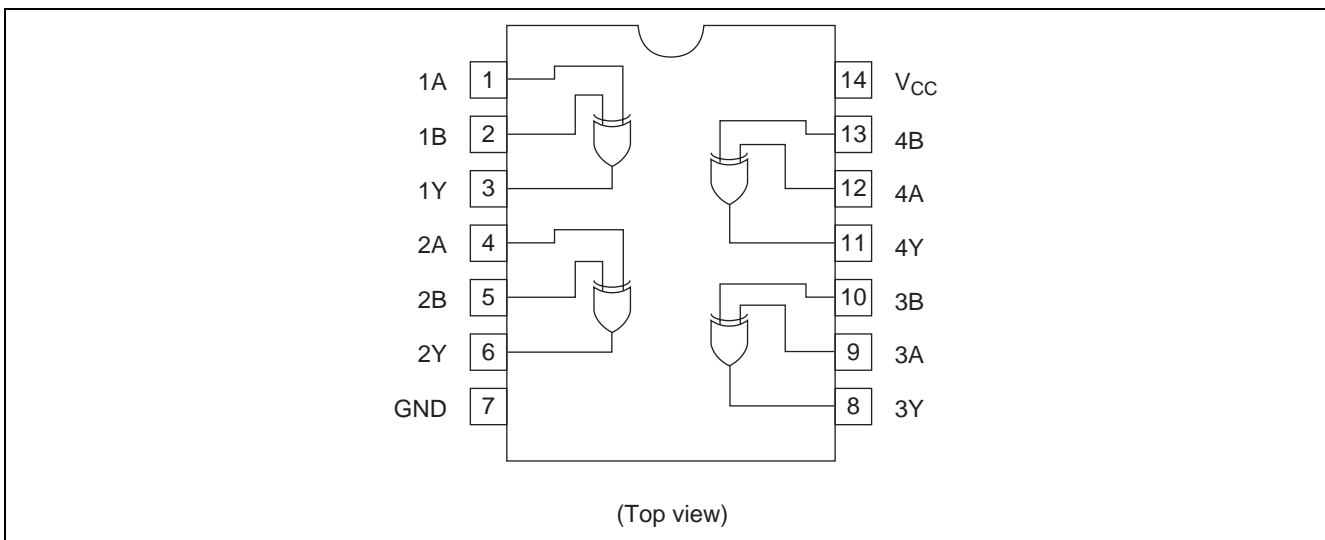
Features

- Ordering Information

Part Name	Package Type	Package Code (Previous Code)	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LS86P	DILP-14 pin	PRDP0014AB-B (DP-14AV)	P	—
HD74LS86FPEL	SOP-14 pin (JEITA)	PRSP0014DF-B (FP-14DAV)	FP	EL (2,000 pcs/reel)
HD74LS86RPEL	SOP-14 pin (JEDEC)	PRSP0014DE-A (FP-14DNV)	RP	EL (2,500 pcs/reel)

Note: Please consult the sales office for the above package availability.

Pin Arrangement



Function Table

Inputs		Outputs
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	L

H; high level, L; low level

Absolute Maximum Ratings

Item	Symbol	Ratings	Unit
Supply voltage	V_{CC}	7	V
Input voltage	V_{IN}	7	V
Power dissipation	P_T	400	mW
Storage temperature	Tstg	-65 to +150	°C

Note: Voltage value, unless otherwise noted, are with respect to network ground terminal.

Recommended Operating Conditions

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	V_{CC}	4.75	5.00	5.25	V
Output current	I_{OH}	—	—	-400	μA
	I_{OL}	—	—	8	mA
Operating temperature	Topr	-20	25	75	°C

Electrical Characteristics

($T_a = -20$ to $+75$ °C)

Item	Symbol	min.	typ.*	max.	Unit	Condition
Input voltage	V_{IH}	2.0	—	—	V	
	V_{IL}	—	—	0.8	V	
Output voltage	V_{OH}	2.7	—	—	V	$V_{CC} = 4.75$ V, $V_{IH} = 2$ V, $V_{IL} = 0.8$ V, $I_{OH} = -400$ μA
	V_{OL}	—	—	0.4	V	
—		—	0.5	$I_{OL} = 8$ mA		$V_{CC} = 4.75$ V, $V_{IH} = 2$ V, $V_{IL} = 0.8$ V
Input current	I_{IH}	—	—	40	μA	$V_{CC} = 5.25$ V, $V_I = 2.7$ V
	I_{IL}	—	—	-0.8	mA	$V_{CC} = 5.25$ V, $V_I = 0.4$ V
	I_I	—	—	0.2	mA	$V_{CC} = 5.25$ V, $V_I = 7$ V
Short-circuit output current	I_{OS}	-20	—	-100	mA	$V_{CC} = 5.25$ V
Supply current**	I_{CC}	—	6.1	10	mA	$V_{CC} = 5.25$ V
Input clamp voltage	V_{IK}	—	—	-1.5	V	$V_{CC} = 4.75$ V, $I_{IN} = -18$ mA

Notes: * $V_{CC} = 5$ V, $T_a = 25$ °C

** I_{CC} is measured with all outputs open and all other inputs grounded.

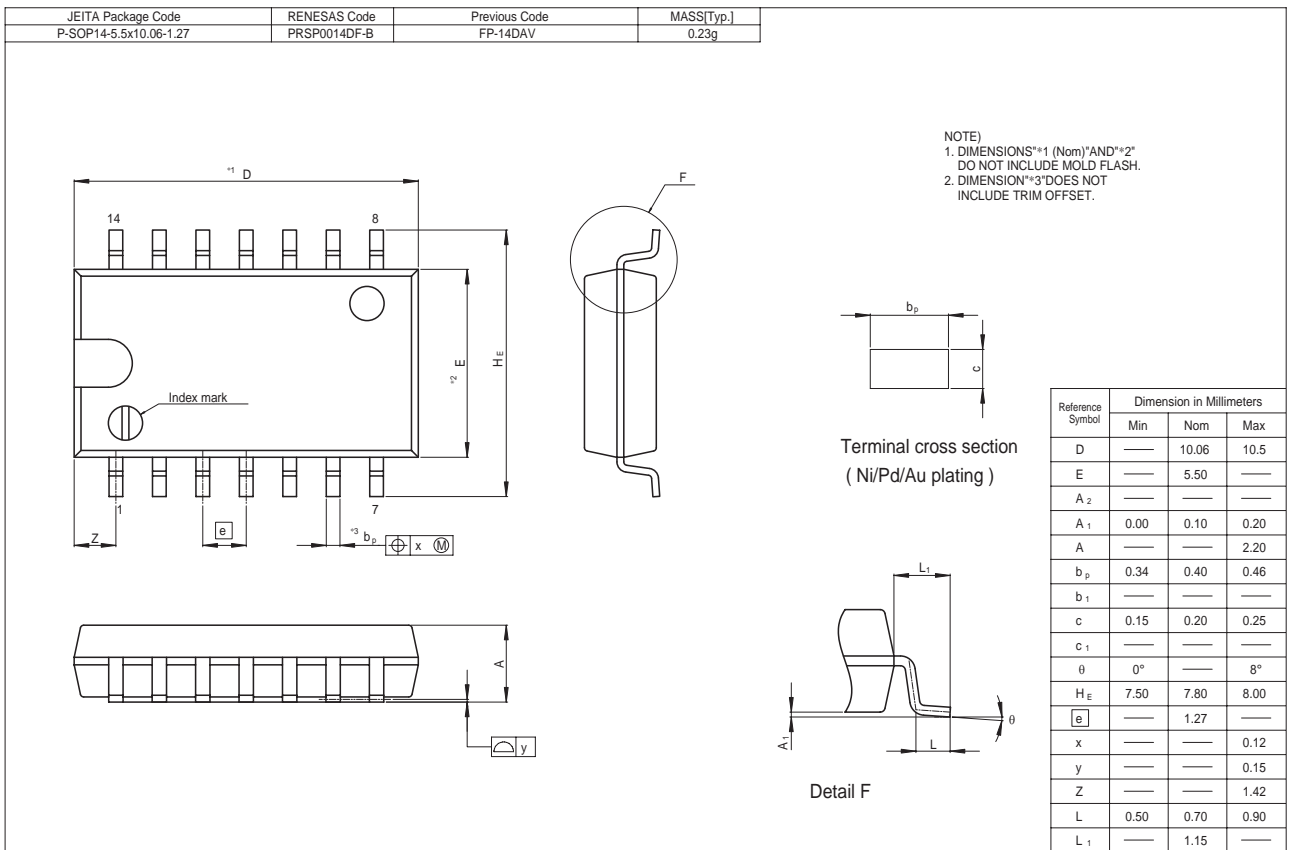
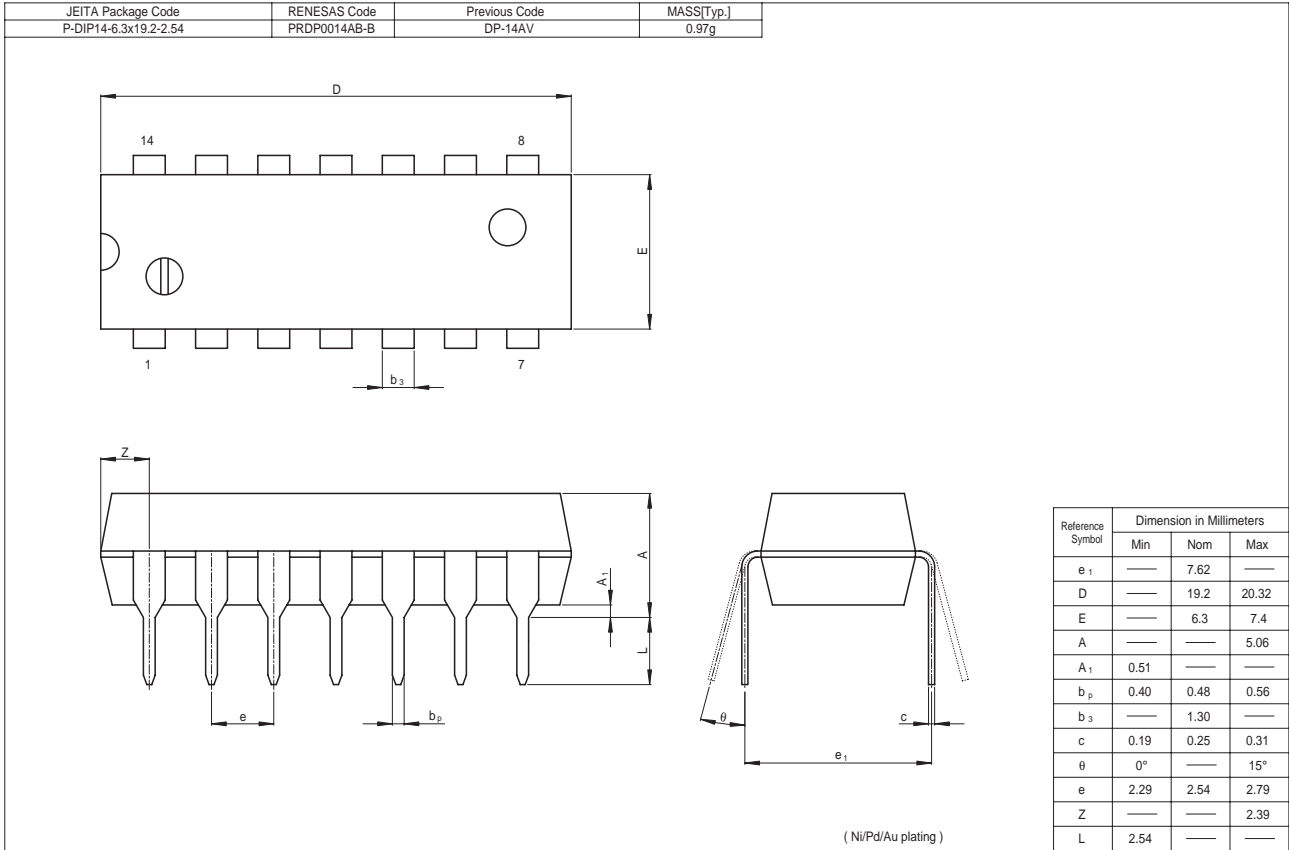
Switching Characteristics

($V_{CC} = 5$ V, $T_a = 25$ °C)

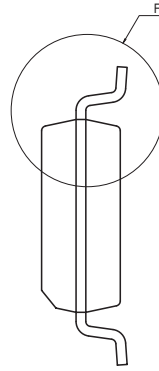
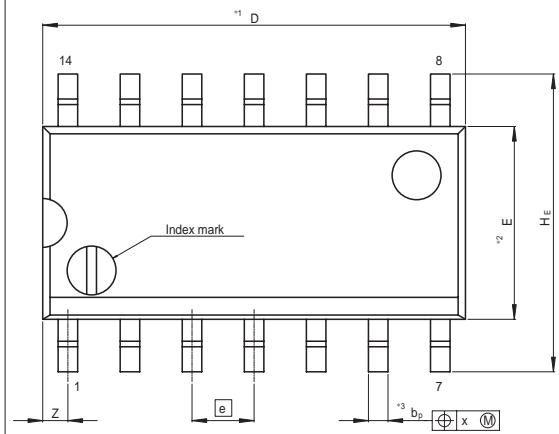
Item	Symbol	Inputs	min.	typ.	max.	Unit	Test Conditions
Propagation delay time	t_{PLH}	A or B	—	12	23	ns	$C_L = 15$ pF, $R_L = 2$ kΩ
	t_{PHL}		—	10	17	ns	
	t_{PLH}	A or B	—	20	30	ns	
	t_{PHL}		—	13	22	ns	

Note: Refer to Test Circuit and Waveform of the Common Item "TTL Common Matter (Document No.: REJ27D0005-0100)".

Package Dimensions

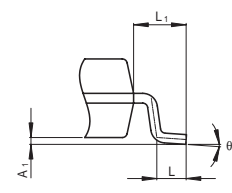


JEITA Package Code P-SOP14-3.95x8.65-1.27	RENESAS Code PRSP0014DE-A	Previous Code FP-14DNV	MASS[Typ.] 0.13g
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NOTE)
1. DIMENSIONS*1 (Nom)*AND*2*
DO NOT INCLUDE MOLD FLASH.
2. DIMENSION*3*DOES NOT
INCLUDE TRIM OFFSET.

Terminal cross section
(Ni/Pd/Au plating)



Detail F

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	—	8.65	9.05
E	—	3.95	—
A ₂	—	—	—
A ₁	0.10	0.14	0.25
A	—	—	1.75
b _p	0.34	0.40	0.46
b ₁	—	—	—
c	0.15	0.20	0.25
c ₁	—	—	—
θ	0°	—	8°
H _E	5.80	6.10	6.20
e	—	1.27	—
x	—	—	0.25
y	—	—	0.15
Z	—	—	0.635
L	0.40	0.60	1.27
L ₁	—	1.08	—

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